

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Thermally Conductive Insulators



THERMALLY CONDUCTIVE ELECTRICALLY INSULATIVE MATERIAL

Tgard™ 100 is a high thermal performance insulator pad consisting of silicone/boron nitrate composite. It is specially designed to maximize high thermal and electrical isolation performance for wide variety of applications.

The unique formulation offers an excellent smooth and compliant surface which minimizes interfacial thermal resistance at low mounting forces. Tgard $^{\text{TM}}$ 100 is ideal for applications that require low component mounting forces include discrete semiconductors mounted with clips.

FEATURES

- High thermal conductivity of 3.5W/mK
- Thermal resistance of 0.279°C-in²/watt @ 50ps
- High dielectric breakdown voltage of 6,000 volts

BENEFITS

- Combines smooth and highly compliant surface with high thermal conductivity
- Unique formulation minimizes thermal resistance at low mounting forces

VALUE

- Unifying cost effectiveness with high thermal and dielectric performance
- Ideal for high performance, high reliability applications

AVAILABILITY

- Samples available in standard sheet size of 18.5" x 18.5" for A0 & 9" x 18" for A1
- Support site for sample and production part in SZ, CLE, LIB and TJ sites respectively

STRATEGY

Who: Switch Mode Power Supplies, Motor controllers, Power conversion equipment **What:** High thermal and dielectric performance with low thermal resistance at low mounting forces

How: Focus on applications requiring excellent performance in thermal and dielectric

TEAM

Engineering: Jack Zhou, Bob Fu

Product: Mark Wisniewski, Troy Derksen, Tom Karwan, Derrick Ho

Technology: Daniel Zhao, Leo Li

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